

Abstract

The invention concerns a method for populating and soldering a circuit board, which is populated with a wired, electrical component having at least one connection wire or pin and a housing or casing thermally critical for conventional, automatic soldering methods. The invention additionally concerns a reflow oven for the soldering of the circuit board and a circuit board for such method.

The invention enables the soldering of the thermally critical component in the reflow oven by using the circuit board itself for the thermal shielding of the thermally critical THT-components against the heat energy acting on the circuit board and required for the soldering. The circuit boards 66 are placed on frames 67 for this purpose, for example, and transported through the reflow oven 60 in such a manner that the thermally critical components are arranged on the under side of the circuit board 66 facing away from the heat energy.

(Fig. 7)